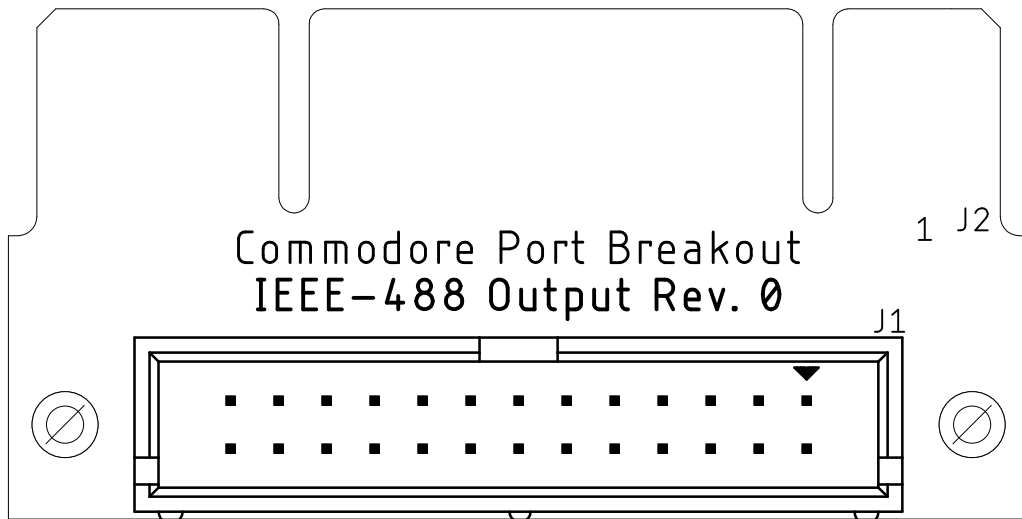
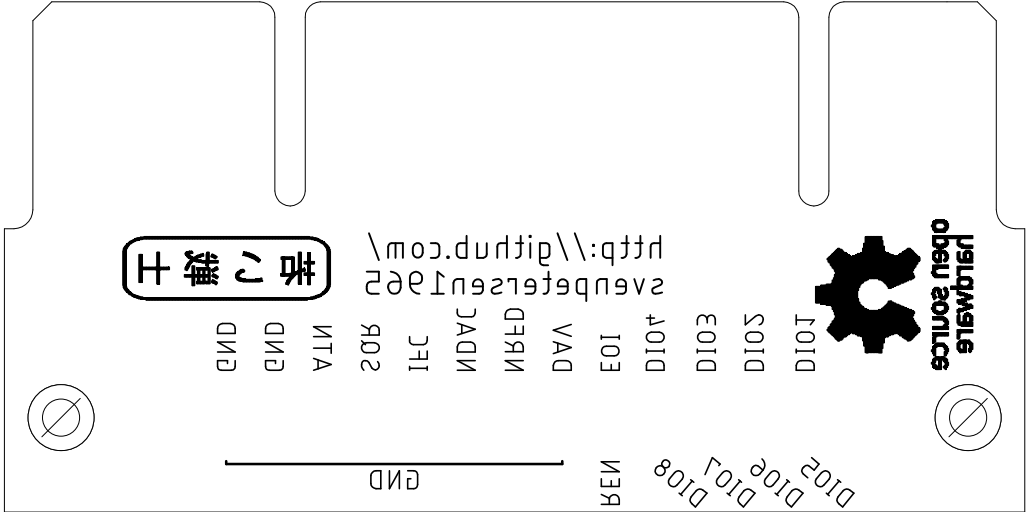




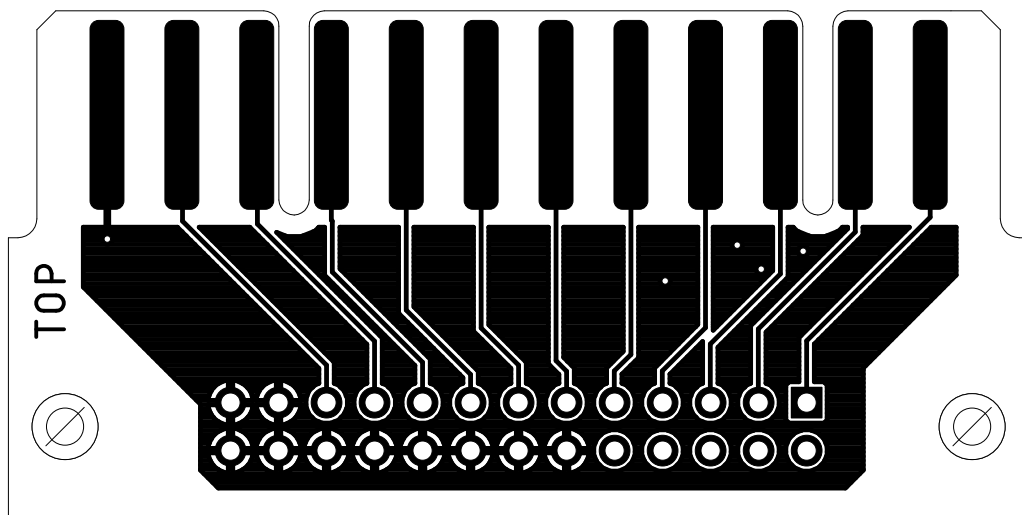
Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35µm	Cu-Layers: 2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
placement component side		



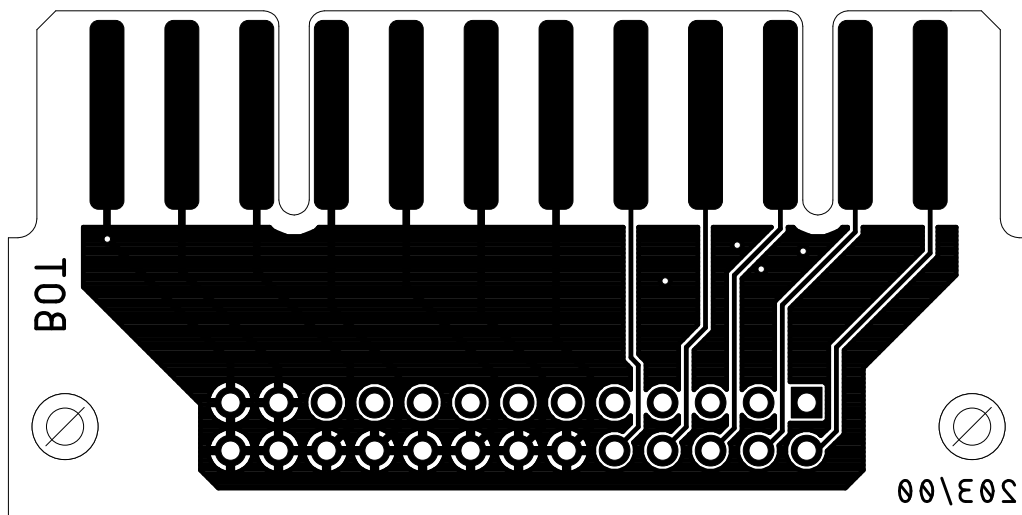
Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35µm	Cu-Layers:2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
place ment for solder tabs		



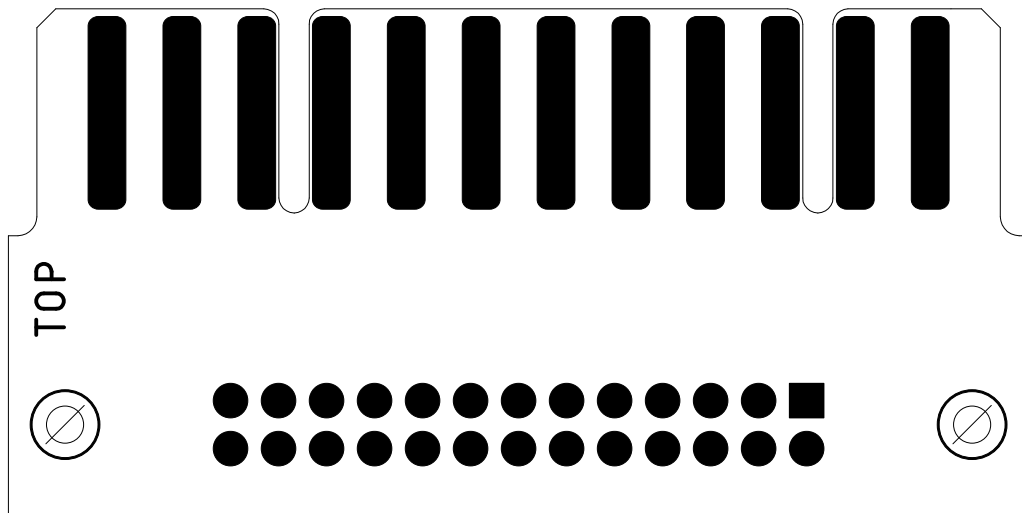
Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35μm	Cu-Layers: 2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
top		



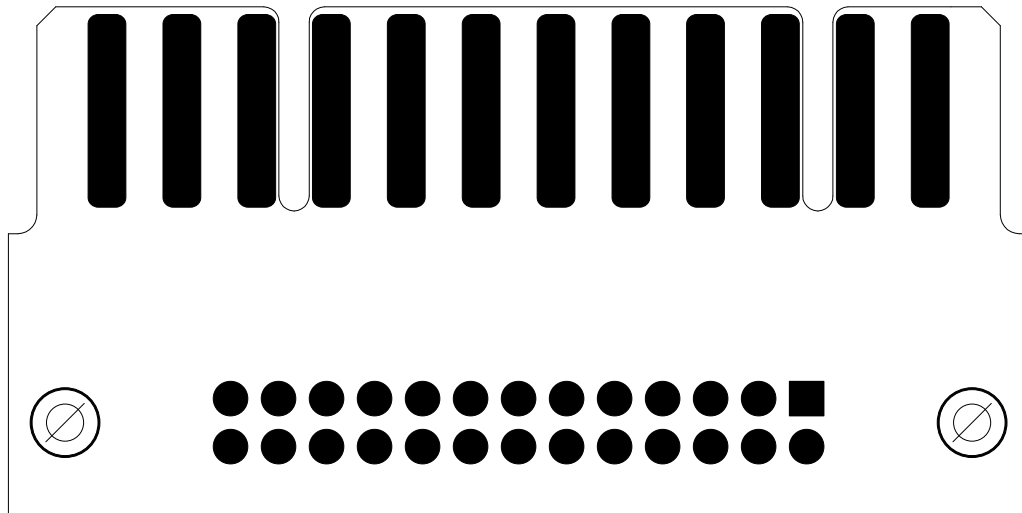
Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35µm	Cu-Layers: 2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
bottom		



Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35µm	Cu-Layers: 2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
stopmask component side		



Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35µm	Cu-Layers: 2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
stopmask solder side		



Sven Petersen 2022	Doc.-No.: 203-2-01-00	
	Cu: 35µm	Cu-Layers:2
CPB_IEEE_out		
12.11.2022 19:25		Rev.: 0
placement component side		measures

